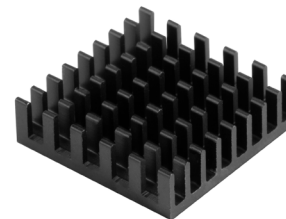


MODEL: HSB08-212106 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



MODEL

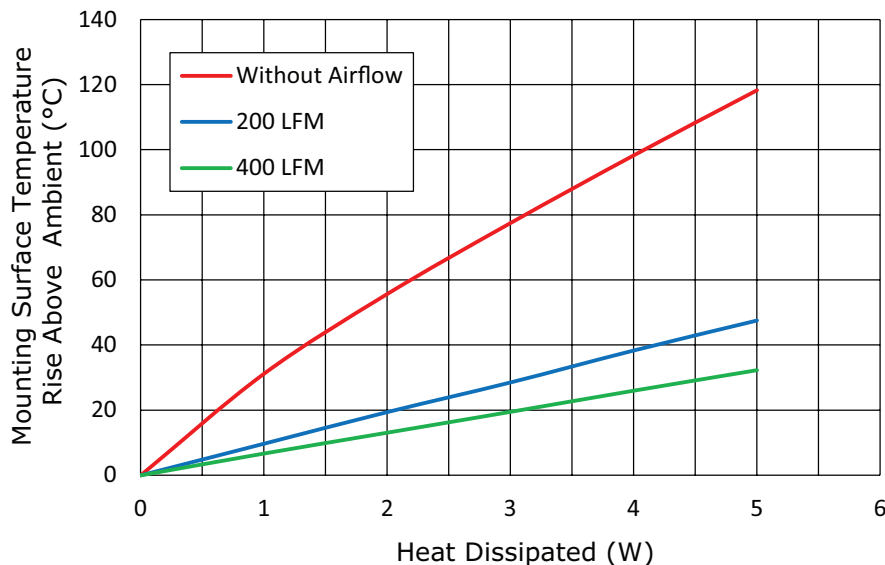
MODEL	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSB08-212106	25.40	31.2	9.7	6.7	2.95

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	31.2	9.7	6.7
2	55.7	19.4	13.1
3	77.5	28.5	19.5
4	98.3	38.3	26.0
5	118.3	47.5	32.3

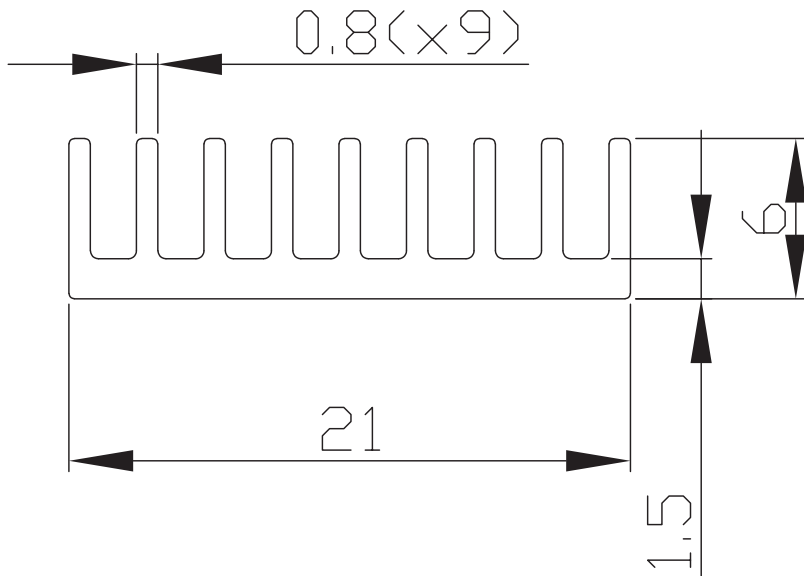
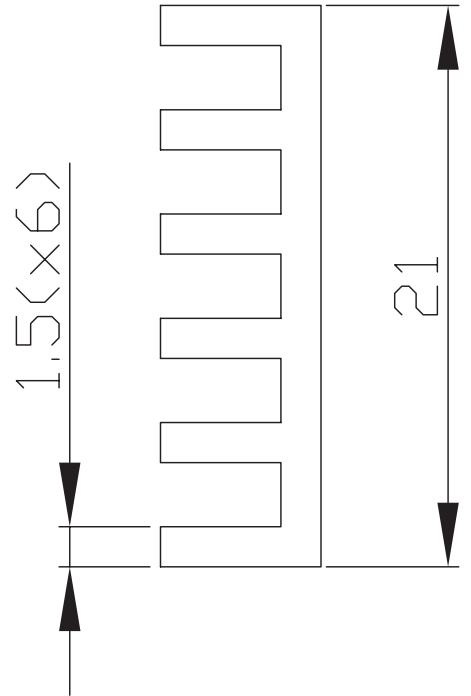
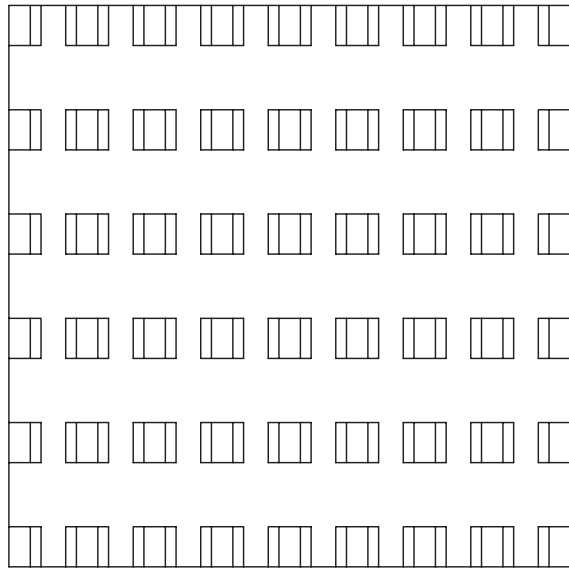
T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.2 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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